



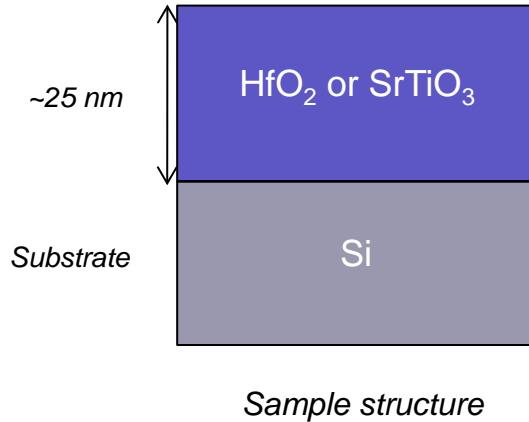
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# Monatomic and Cluster Argon Ion XPS Depth Profiling of $\text{SrTiO}_3$ and $\text{HfO}_2$

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# Introduction: Depth profiling of metal oxide layers

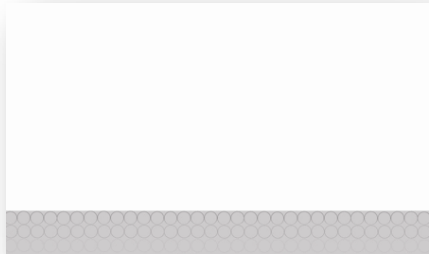


- $\text{HfO}_2$  or  $\text{SrTiO}_3$  layer on Si substrate
- Problem
  - What is the stoichiometry of the film as a function of depth?
  - Traditional monatomic  $\text{Ar}^+$  sputtering causes changes in oxidation state when profiling metal oxides
  - How can we profile through the sample, keeping the chemistry intact?
  - Argon clusters with  $\geq 2000$  atoms are good for profiling through organic layers with minimal chemical damage
    - These large clusters etch too slowly with inorganic materials

# Introduction: Monatomic *versus* cluster profiling



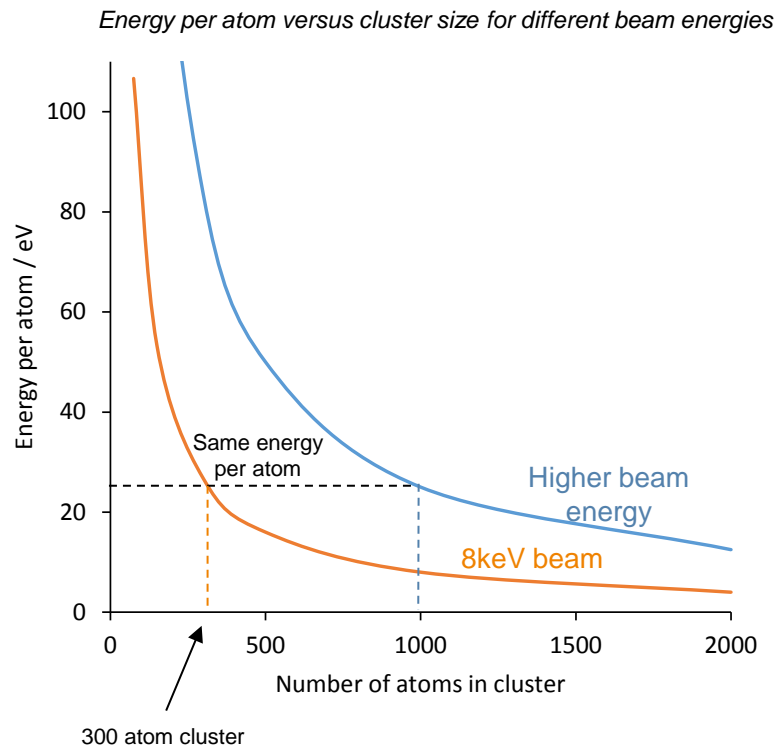
- Monatomic ions ( $\text{Ar}^+$ )
  - High energy per atom (200eV – 4keV)
  - High etch rate
  - Deep surface penetration
  - Can damage surface chemistry
  - Ideal for etching inorganic material



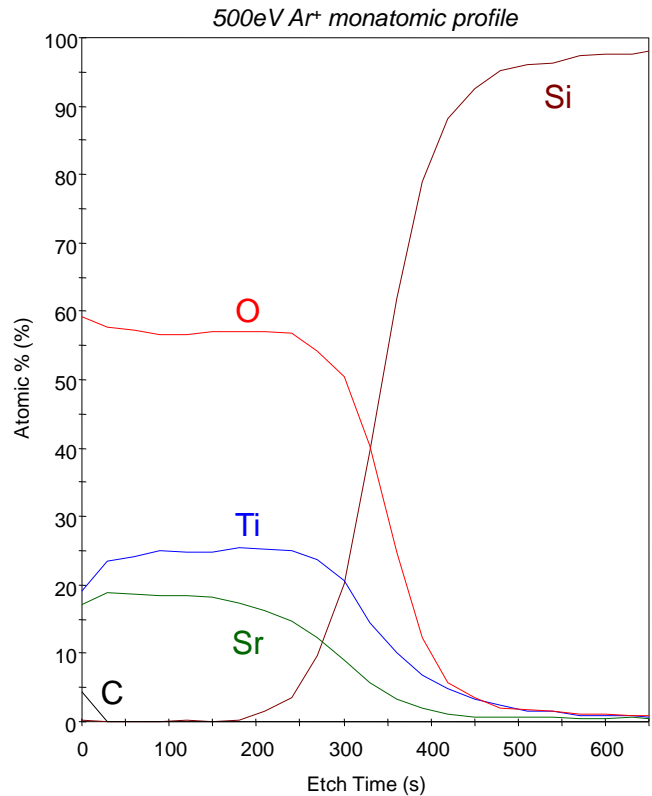
- Cluster ions ( $\text{Ar}_n^+$ )
  - Low energy per atom (1eV – 100eV)
  - Minimal surface penetration
  - Non-damaging to surface chemistry
  - Low etch rate for large clusters
  - Large clusters ideal for etching organic material



# Introduction: Small clusters for inorganic profiling



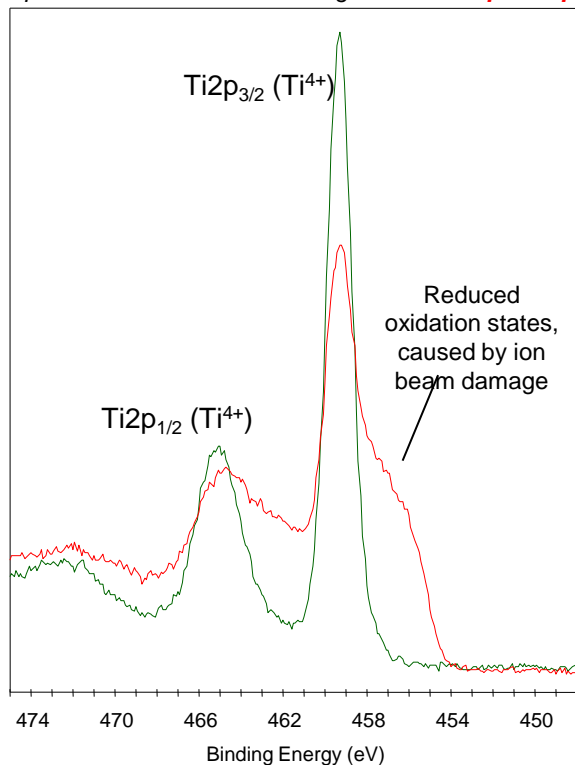
# Monatomic Argon profile - SrTiO<sub>3</sub> film on Si



- Monatomic Argon profile
  - 500eV beam energy
  - Sr:Ti ratio is expected to be 1:1 throughout film but ~0.75:1 observed instead
  - Monatomic Argon beam is modifying the stoichiometry of the film

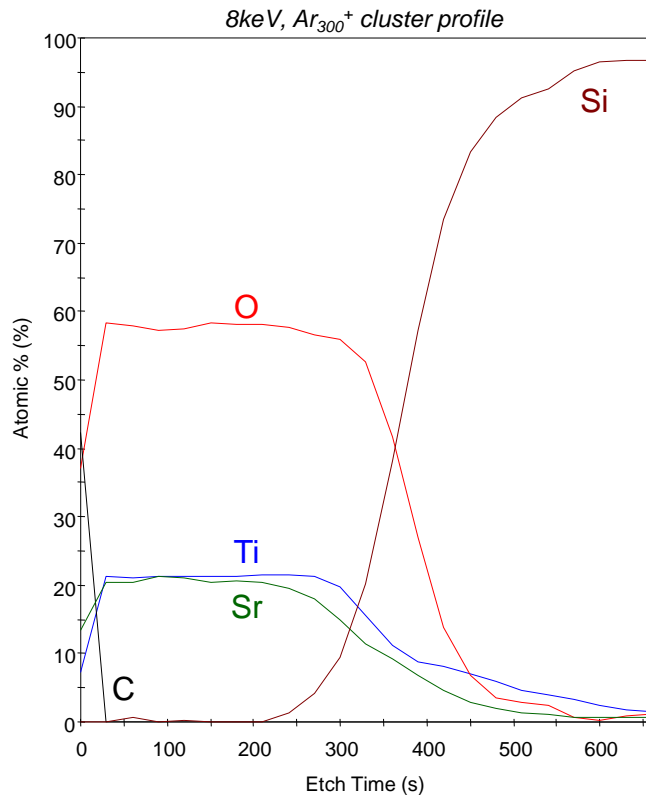
# Monatomic Argon profile – Titanium chemistry SrTiO<sub>3</sub> film on Si

Ti2p spectra **as received** and during **500eV Ar<sup>+</sup> sputter profile**



- Monatomic Argon profile
  - Ti2p spectrum from as received surface shows only peaks due to Ti<sup>4+</sup> chemical state (as expected for SrTiO<sub>3</sub>)
  - After only 90s of 500eV Ar<sup>+</sup> profiling, a significant intensity of lower oxidation states (Ti<sup>3+</sup>, Ti<sup>2+</sup>) are observed in the spectrum
  - ~45% of the Ti2p spectrum is due to these damaged states after 500eV sputtering

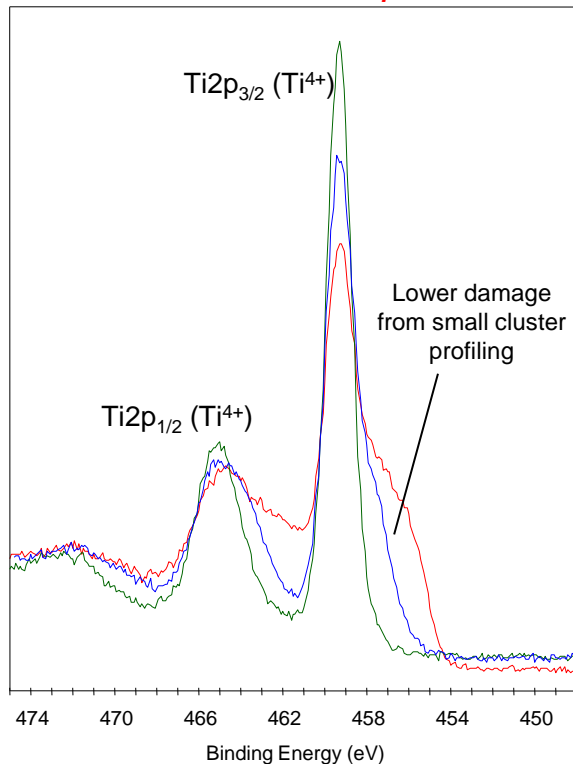
# Argon small cluster profile - SrTiO<sub>3</sub> film on Si



- Argon small cluster profile
  - 8keV, Ar<sub>300</sub><sup>+</sup> small cluster beam
  - Etch rate is comparable to the 500eV monatomic profile (0.07 nm/s)
  - With small cluster profiling, the Sr:Ti ratio is much closer to the expected 1:1 value
  - Small cluster beam is much better at preserving the elemental composition of the SrTiO<sub>3</sub> film, compared to the 500eV monatomic beam

# Argon small cluster profile – Titanium chemistry - SrTiO<sub>3</sub> film on Si

Ti2p spectra *as received*, during 8keV Ar<sub>300</sub><sup>+</sup> sputter profile  
and 500eV monatomic profile

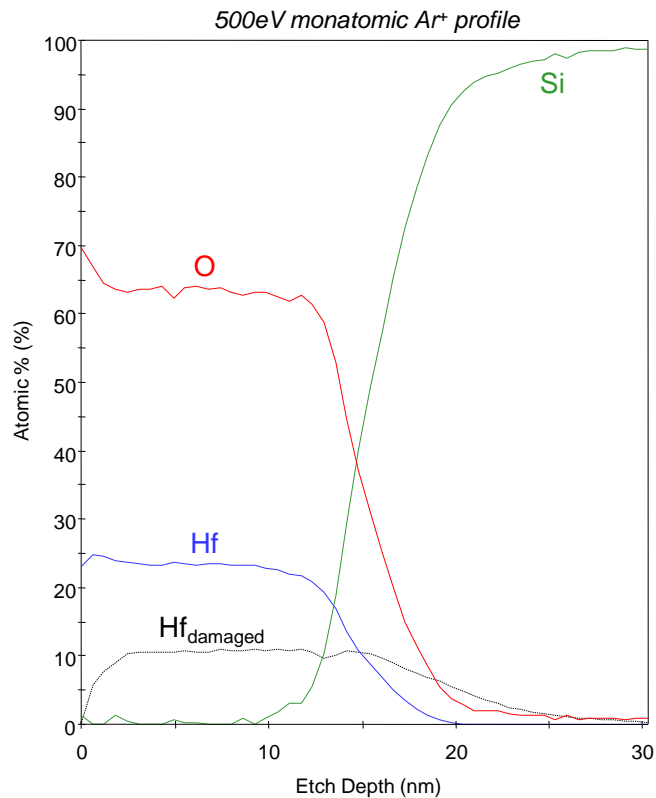


- Argon small cluster profile

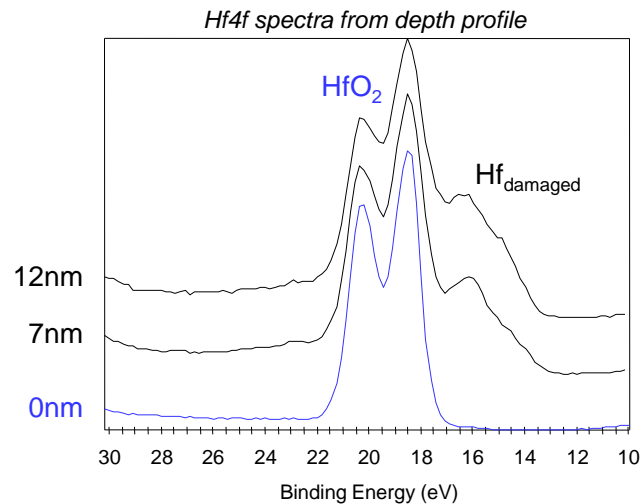
- Ti2p spectrum from as received surface shows only peaks due to Ti<sup>4+</sup> chemical state (as expected for SrTiO<sub>3</sub>)
- After 90s of 8keV Ar<sub>300</sub><sup>+</sup> profiling, the damage to the titanium is considerably lower than was observed for the 500eV monatomic beam
- Small cluster profiling only caused the production of Ti<sup>3+</sup> states, whereas monatomic profiling generated Ti<sup>3+</sup> and the more reduced Ti<sup>2+</sup> state in similar quantities



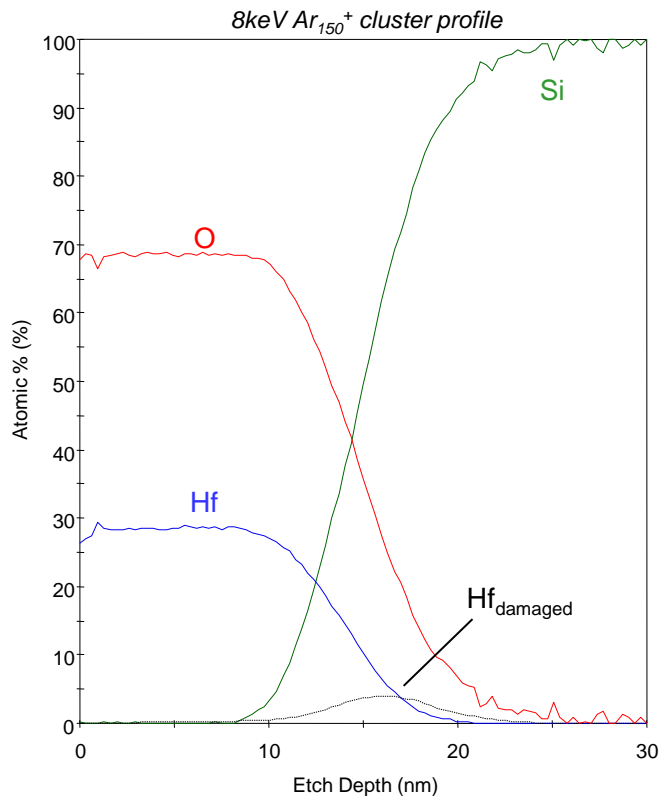
# Low energy (500eV) monatomic Argon profile - HfO<sub>2</sub> film on Si



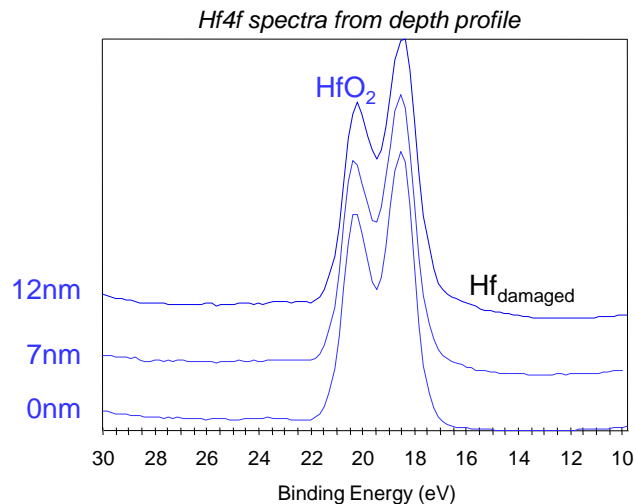
- Significant change in [Hf]/[O] ratio in top few nm, caused by preferential sputtering of oxygen
- Damage to Hf chemistry, as observed in Hf4f spectra (almost 50% on total Hf concentration in film)
- Prolonged tailing of Hf damaged into Si substrate

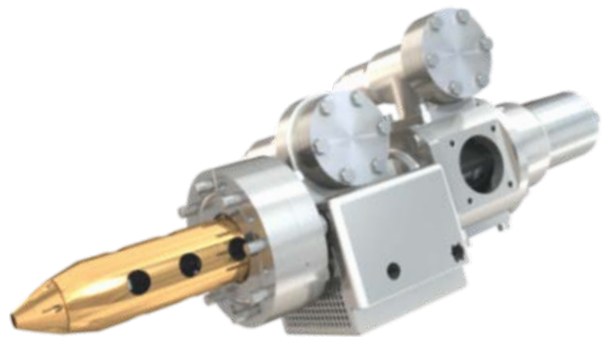


# Small Argon cluster (8keV, Ar<sup>+</sup><sub>150</sub>) sputter profile - HfO<sub>2</sub> film on Si



- Sample tilted to give more glancing ion incidence during sputtering
- Constant [Hf]/[O] ratio throughout film (minimal preferential sputtering of oxygen)
- No significant damage to Hf chemistry, until well into interface region (much less damage compared to 500eV monatomic mode)





*Thermo Scientific Monatomic and Gas  
Cluster Ion Source (MAGCIS)*

- Small cluster profiling of HfO<sub>2</sub> and SrTiO<sub>3</sub> films
- Monatomic and Gas Cluster Ion Source
  - Comprehensive XPS profiling with small Argon clusters (75-300 atoms) enables HfO<sub>2</sub> films to be analysed with lower chemical damage than monatomic Argon